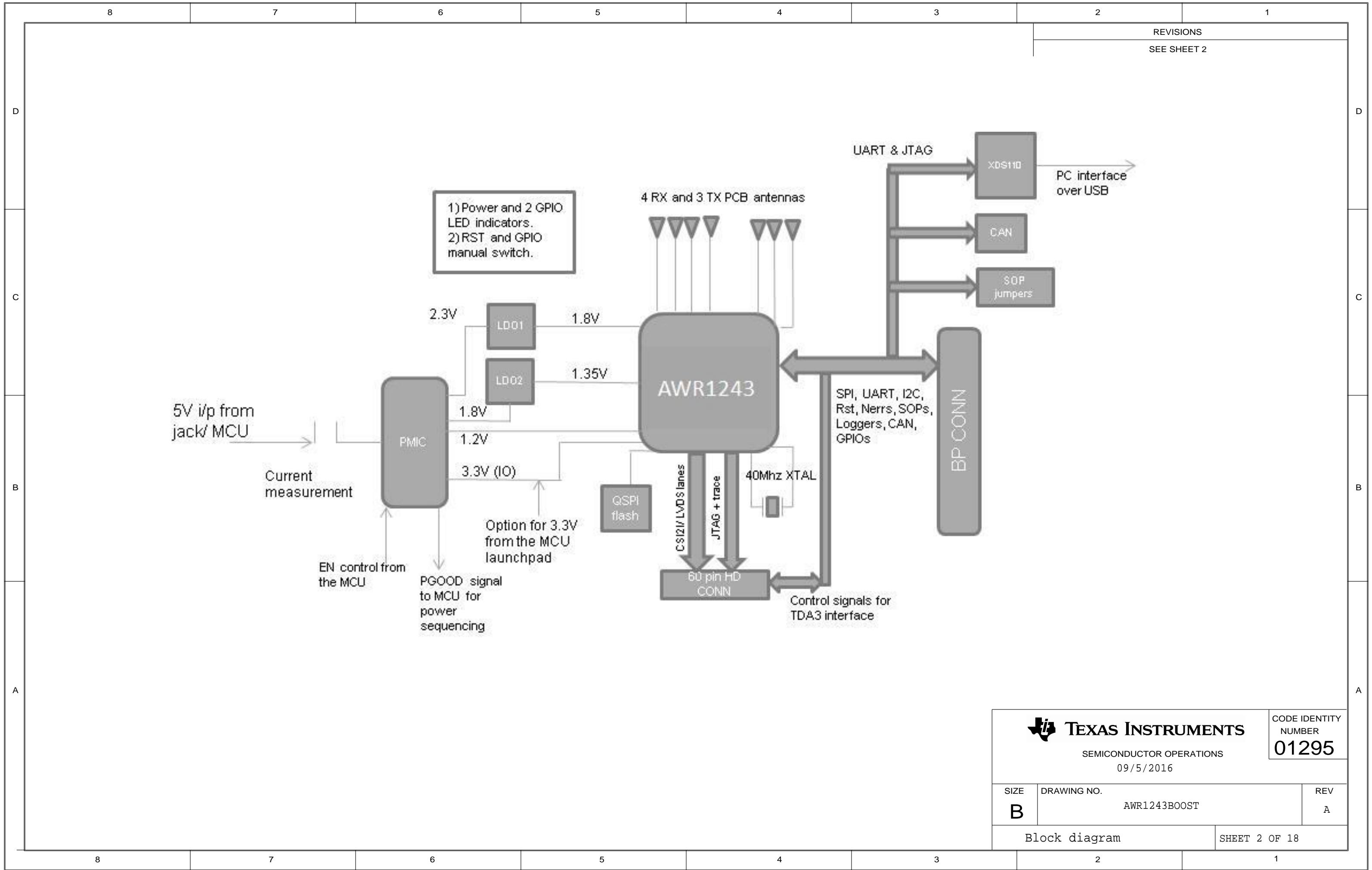
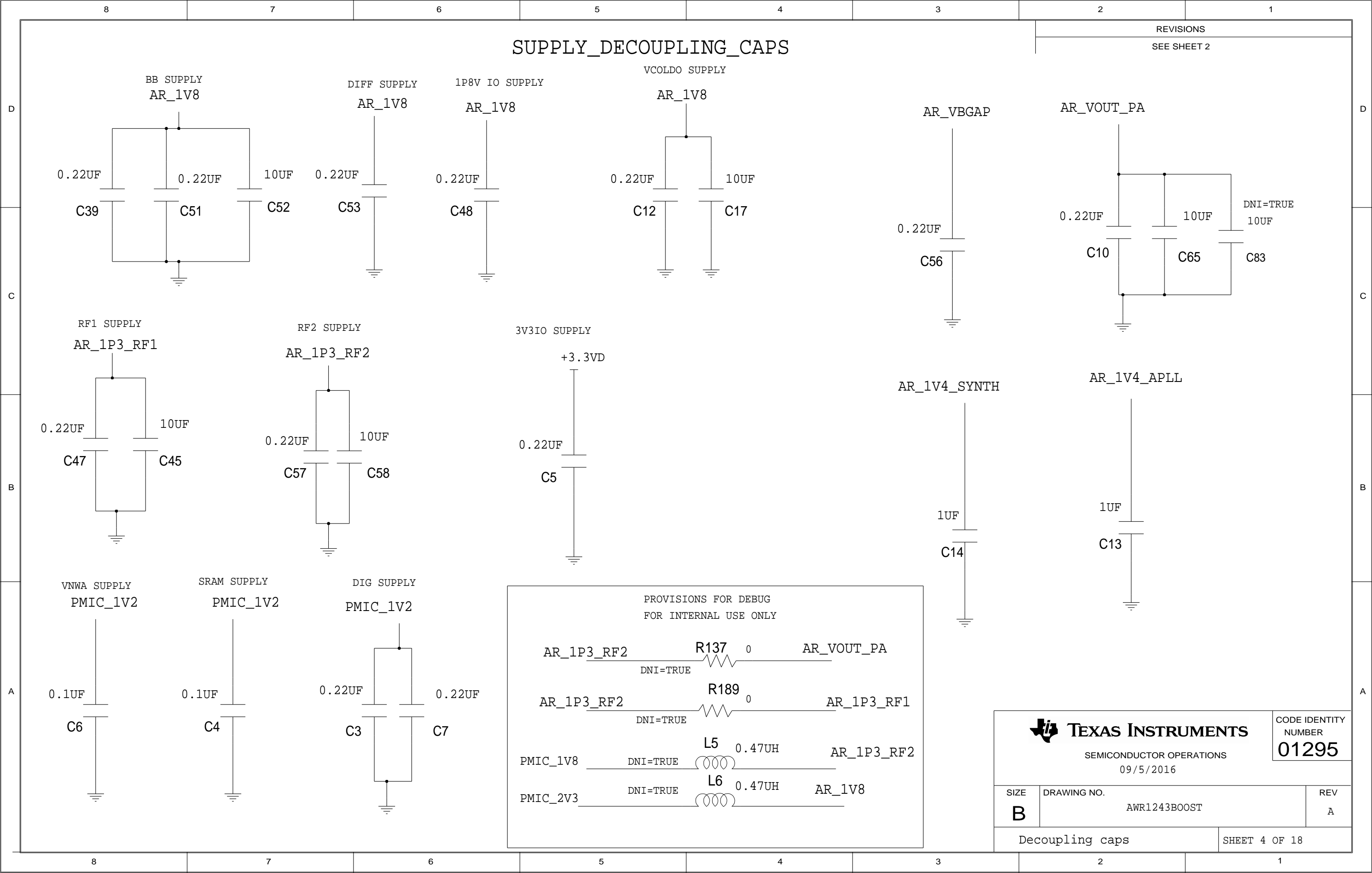


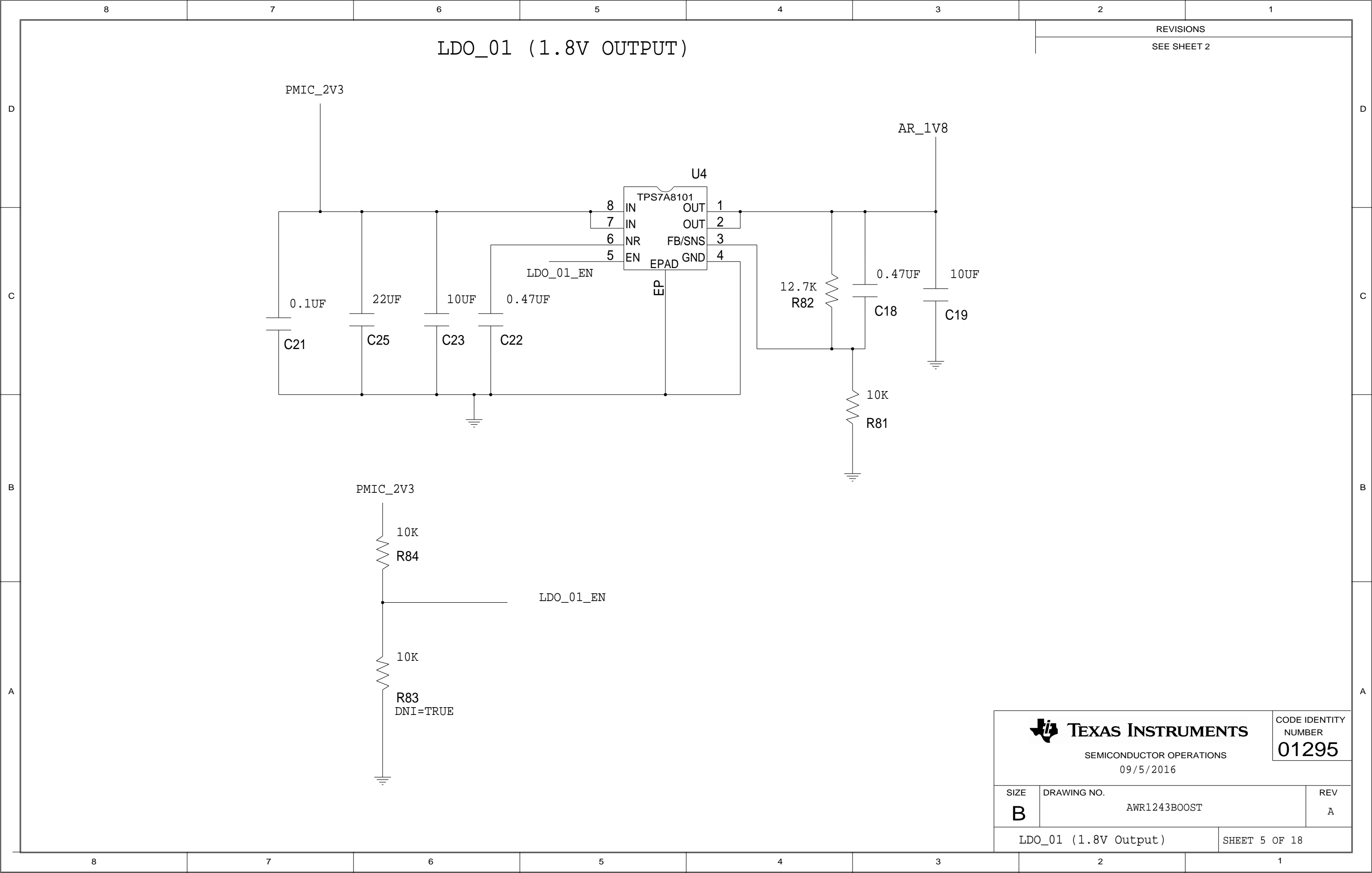
8	7	6	5	4	3	2	1
AWR1243BOOSTPROC010						REVISIONS	
						SEE SHEET 2	
TABLE OF CONTENTS							
SHEET NO.		SHEET NAME					
1		Contents					
2		Block diagram					
3		DUT					
4		Decoupling caps					
5		LDO_01 (1.8V Output)					
6		LDO_02 (1.3V Output)					
7		Pwr_RST_LEDs					
8		PMIC					
9		Flash Section					
10		LP Connector					
11		HD Connector					
12		XDS110 Interface_1A					
13		XDS110 Interface_1B					
14		CAN Interface					
15		SOP selection					
16		Tempsensor					
17		Revision_History					
18		Hardware					
ASSEMBLY NOTES:							
ASSEMBLIES MUST BE CLEAN AND FREE FROM FLUX AND ALL CONTAMINANTS. USE OF NO CLEAN FLUX IS NOT ACCEPTABLE							
ASSEMBLIES MUST COMPLY WITH WORKMANSHIP STANDARDS IPC-A-610 CLASS 2, UNLESS OTHERWISE SPECIFIED							
COMPONENTS MARKED "DNI = TRUE" WILL NOT BE ASSEMBLED							
						CODE IDENTITY NUMBER	
						01295	
						SEMICONDUCTOR OPERATIONS	
						09/5/2016	
SIZE		DRAWING NO.				REV	
B		AWR1243BOOST				A	
Contents						SHEET 1 OF 18	
8	7	6	5	4	3	2	1



<b>TEXAS INSTRUMENTS</b>		CODE IDENTITY NUMBER <b>01295</b>
SEMICONDUCTOR OPERATIONS 09/5/2016		
SIZE <b>B</b>	DRAWING NO. AWR1243BOOST	REV A
Block diagram		SHEET 2 OF 18

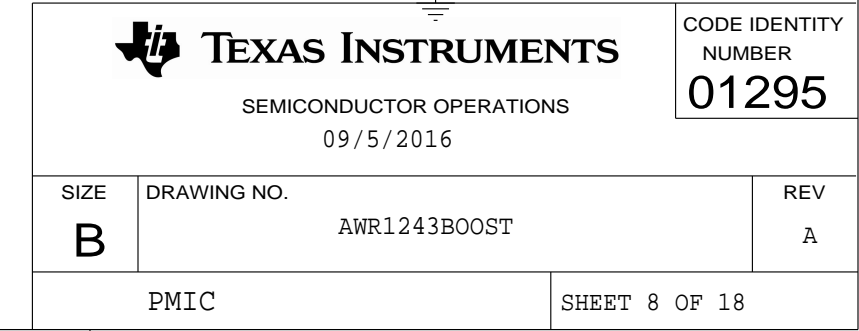










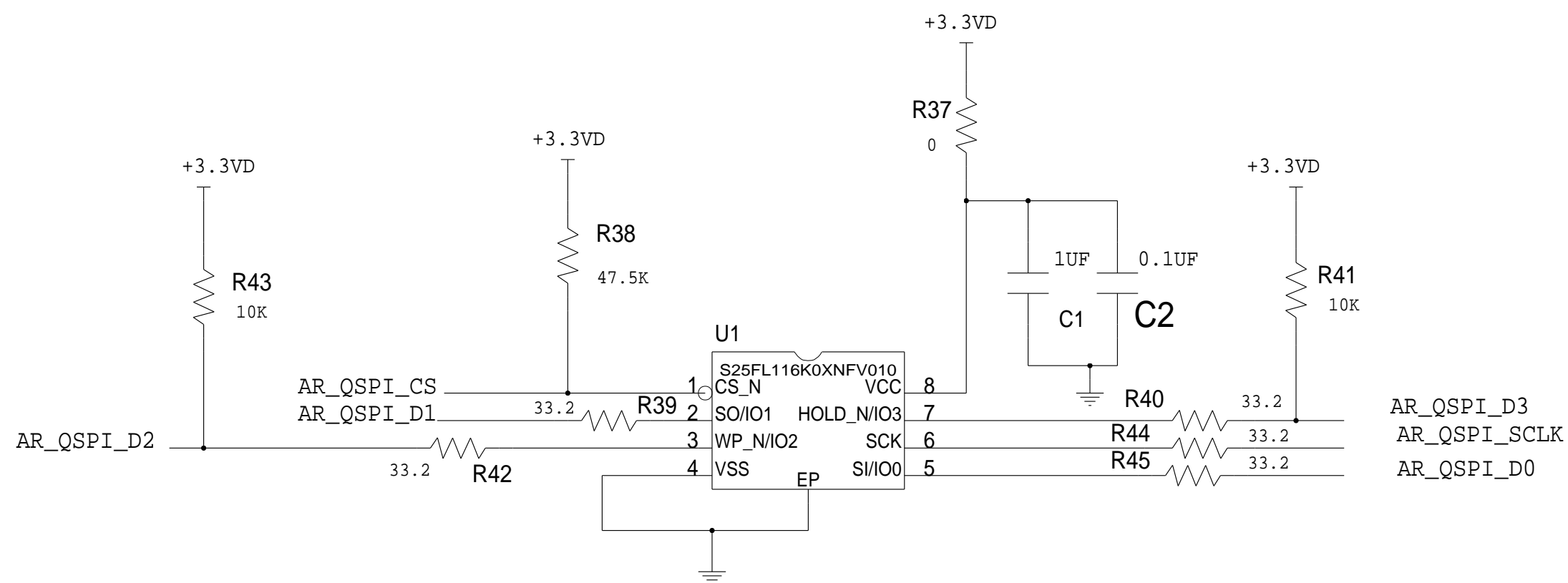




## REVISIONS

SEE SHEET 2

## QSPI FLASH



**TEXAS INSTRUMENTS**

SEMICONDUCTOR OPERATIONS  
09/5/2016

CODE IDENTITY NUMBER	
-------------------------	--

01295

SIZE

**B**

DRAWING NO.
-------------

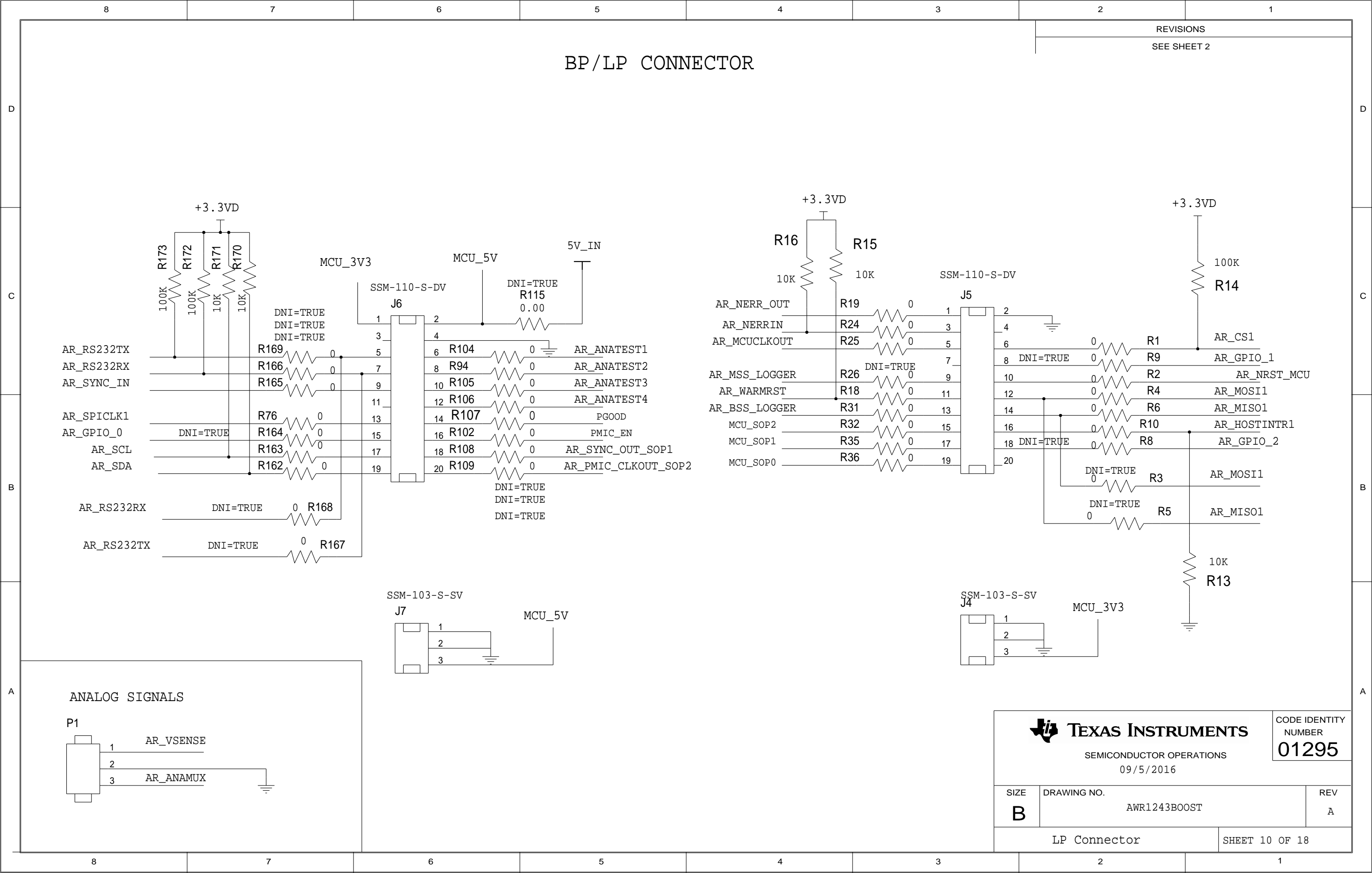
AWR1243BOOST

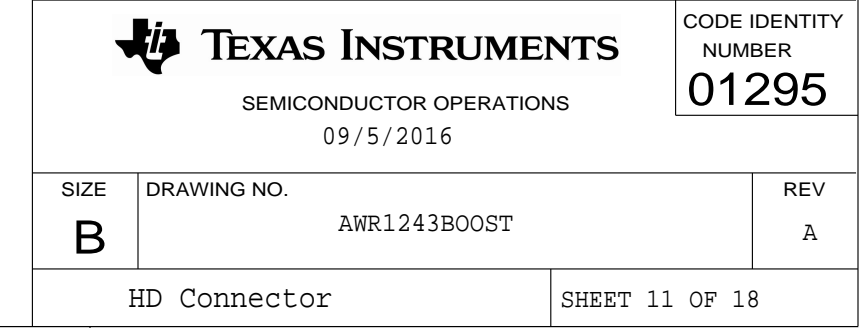
REV

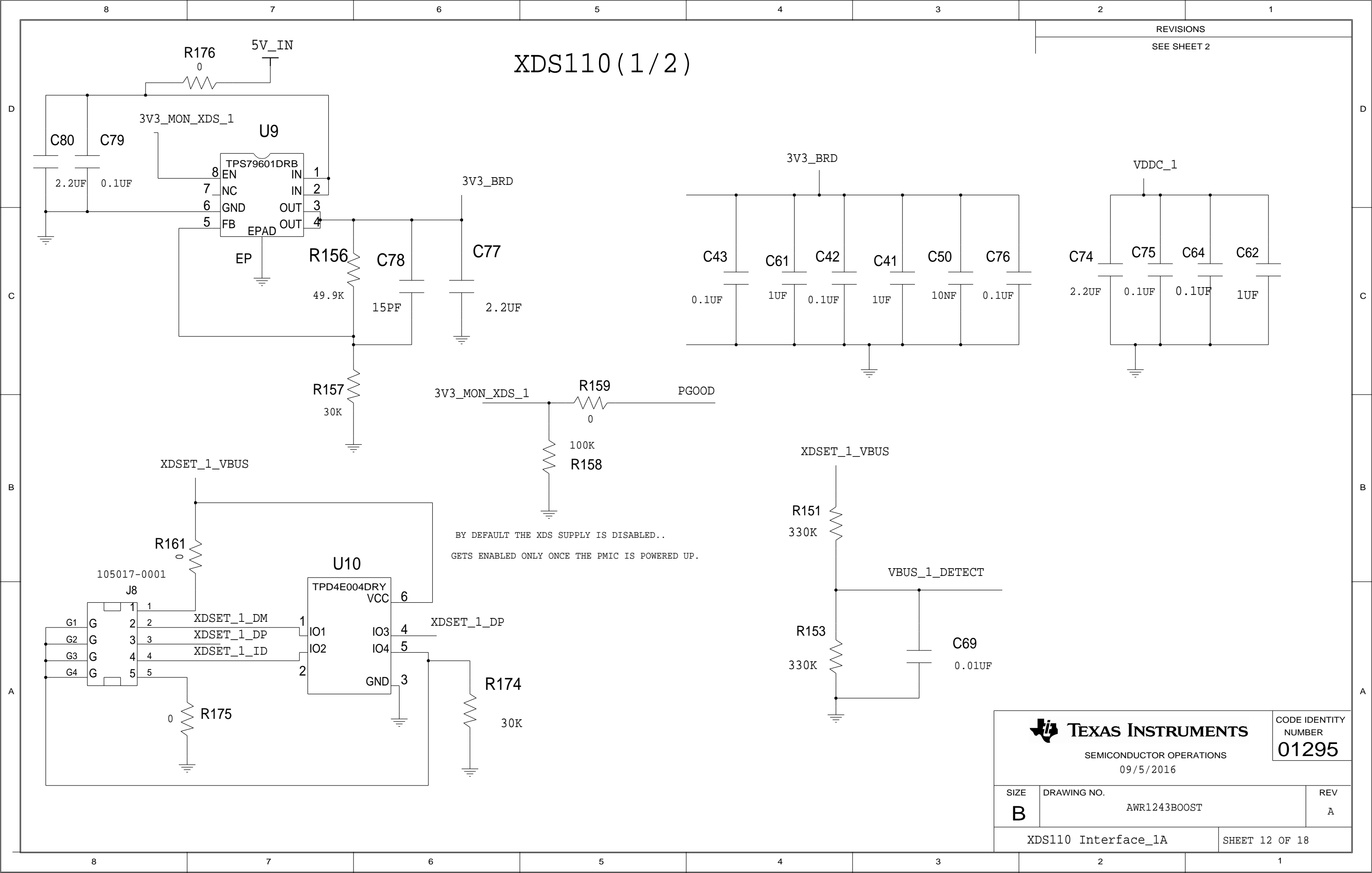
A

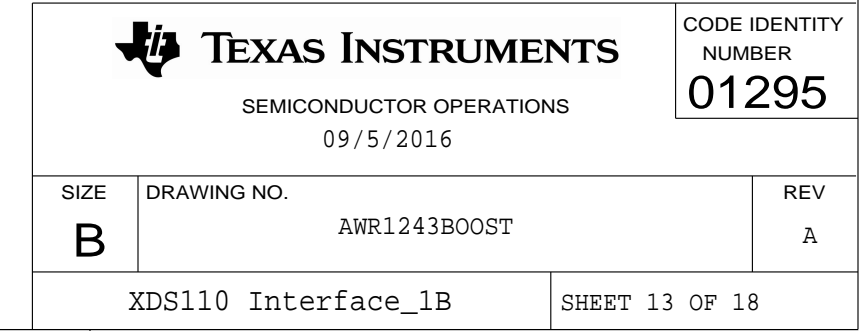
Flash Section

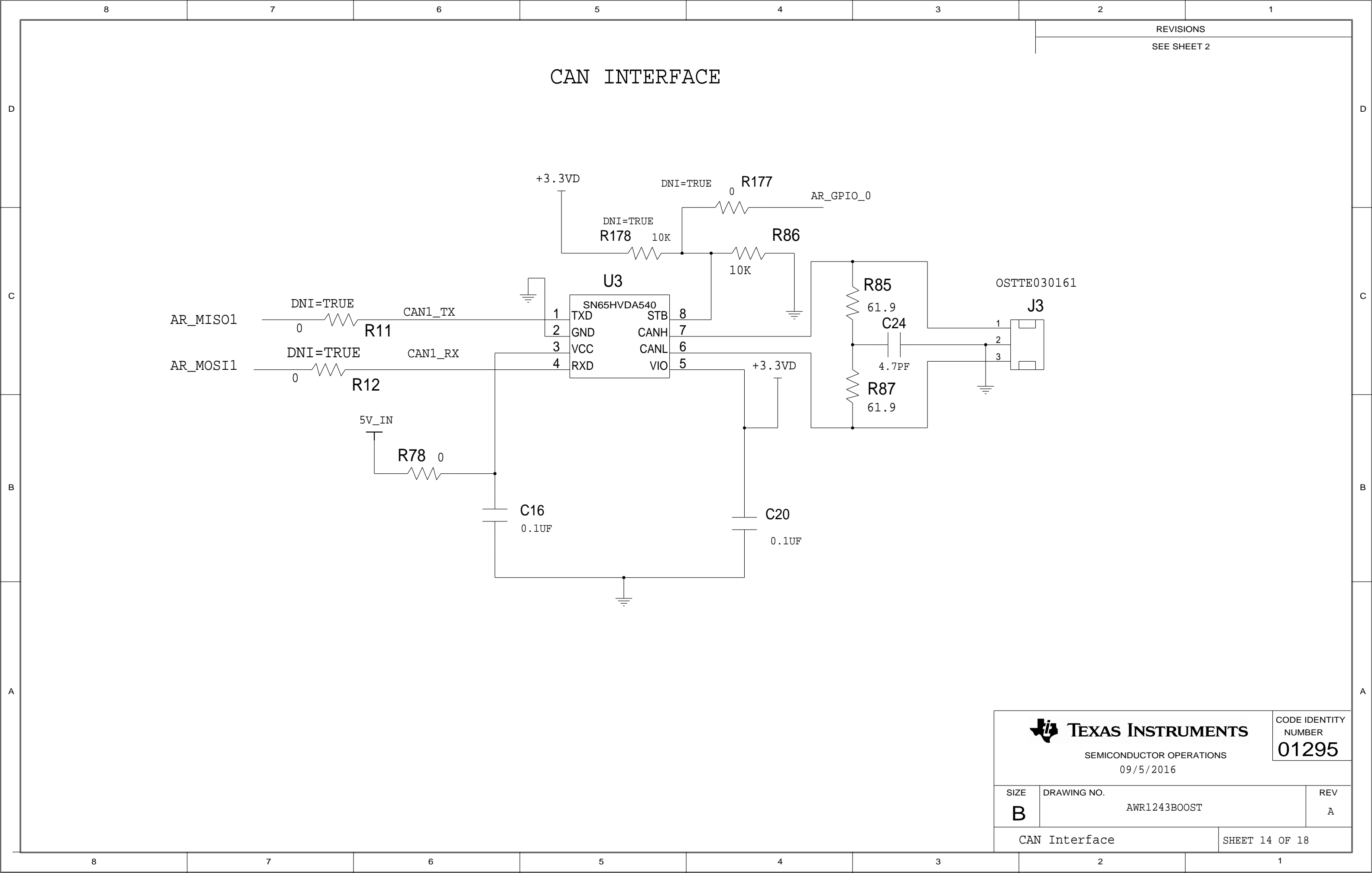
SHEET 9 OF 18




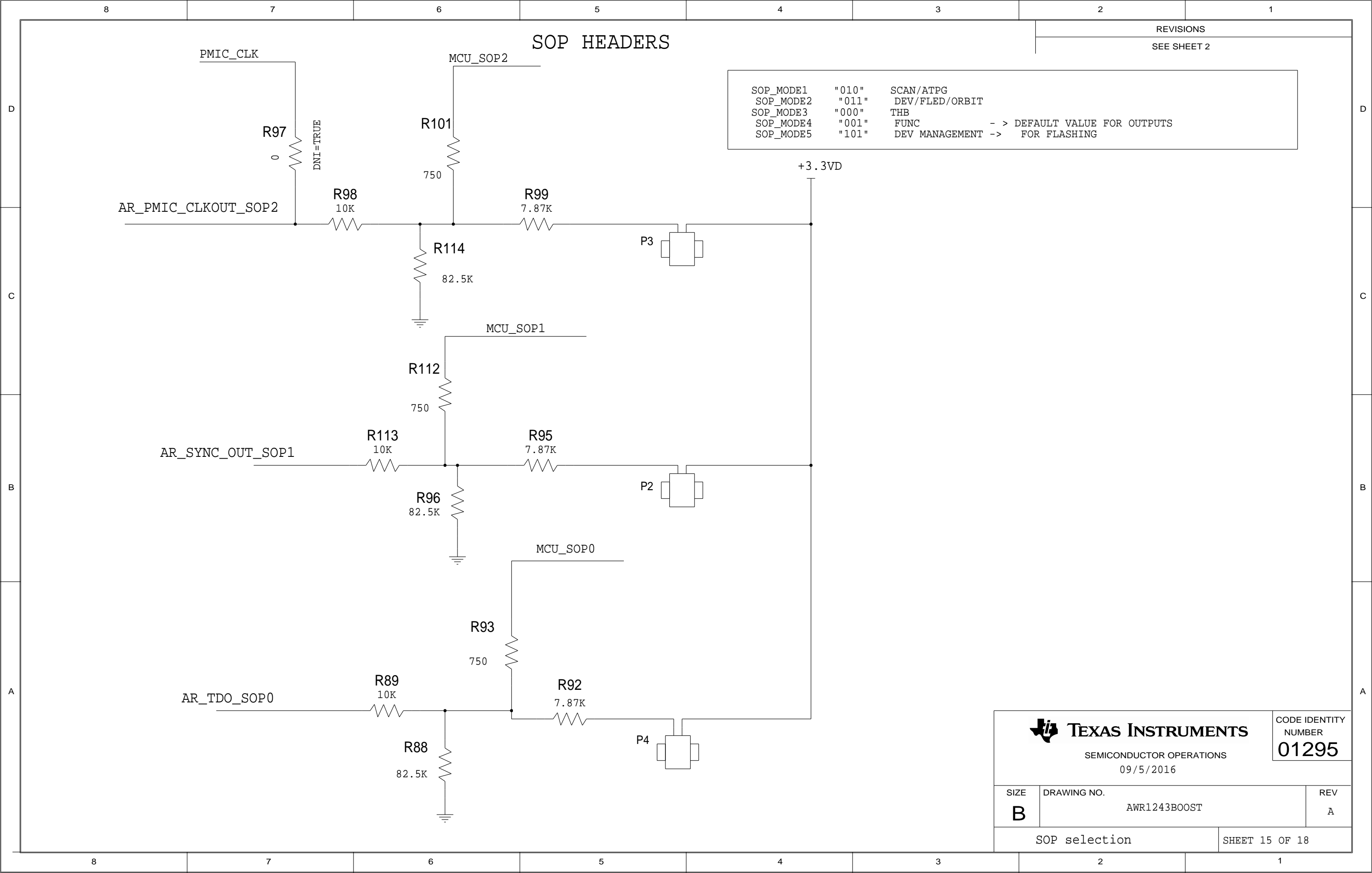









 <b>TEXAS INSTRUMENTS</b>		CODE IDENTITY NUMBER <b>01295</b>
SEMICONDUCTOR OPERATIONS 09/5/2016		
SIZE <b>B</b>	DRAWING NO. AWR1243BOOST	REV A
CAN Interface		SHEET 14 OF 18



 **TEXAS INSTRUMENTS**

SEMICONDUCTOR OPERATIONS

09/5/2016

CODE IDENTITY NUMBER

01295

SIZE

B

DRAWING NO.

AWR1243BOOST

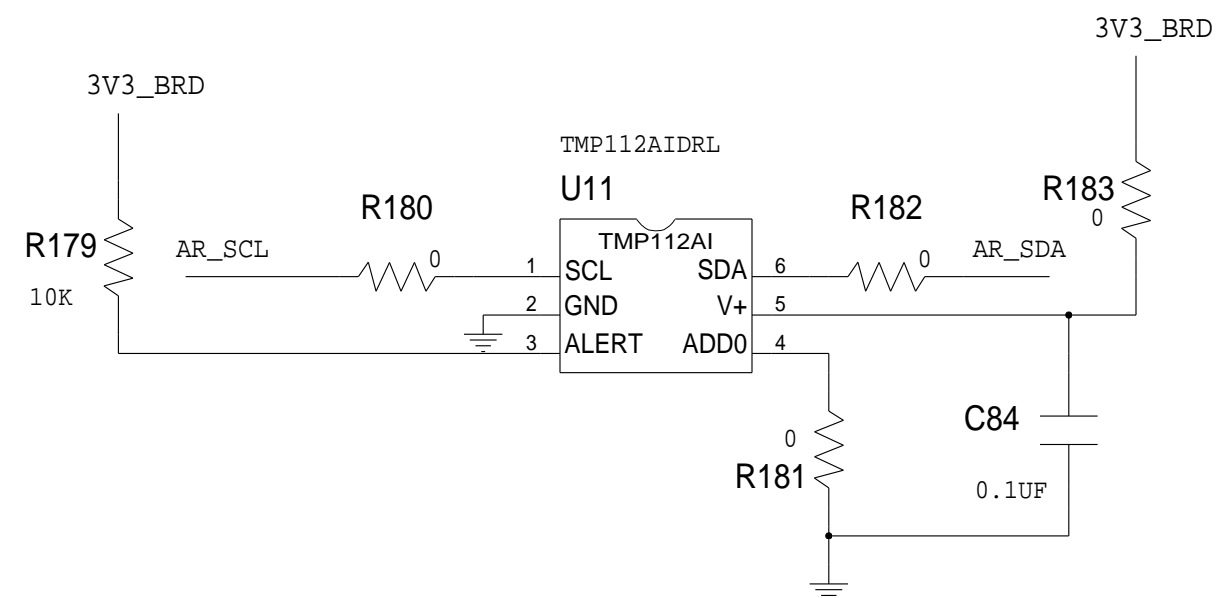
REV

A

SOP selection

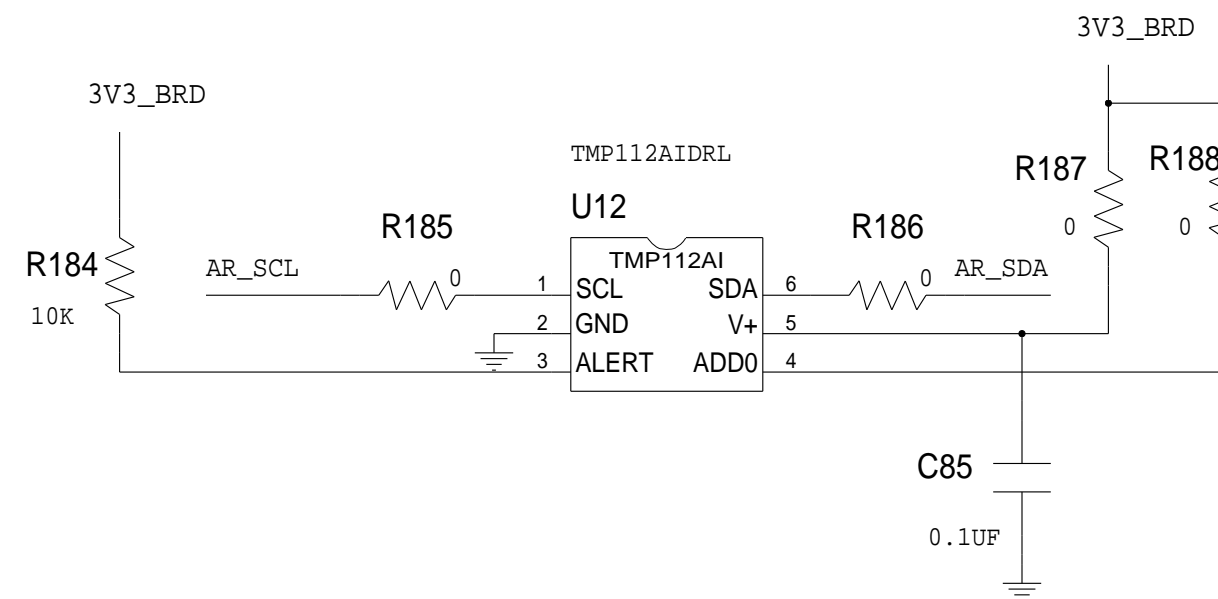
SHEET 15 OF 18

## ONBOARD TEMP SENSORS



TEMP SENSOR CLOSE TO PMIC

DEFAULT I2C ADDRESS : 0X48



TEMP SENSOR AWAY FROM PMIC  
AND MMWAVE DEVICE

DEFAULT I2C ADDRESS : 0X49



**TEXAS INSTRUMENTS**

SEMICONDUCTOR OPERATIONS  
09/5/2016

CODE IDENTITY NUMBER
-------------------------

01295

SIZE
------

B

DRAWING NO.
-------------

AWR1243BOOST

REV

A

Tempsensor

SHEET 16 OF 18



## REVISIONS

SEE SHEET 2

## REVISION HISTORY

CHANGES IN REV A

- 1) ADDED ZENER DIODE ON 5V INPUT TO PROTECT FROM HIGH VOLTAGES.
- 2) ADDED ONBOARD TEMPERATURE SENSORS.
- 3) ADDED FERRITE BEAD ON 5V SUPPLY.
- 4) CHANGED THE PMIC PART TO PG2.2 VERSION
- 5) ADDED DUMMY ANTENNAS FOR RX
- 6) ADDED PM DUBUG PROVISION FOR LDO BYPASS



**TEXAS INSTRUMENTS**

SEMICONDUCTOR OPERATIONS  
09/5/2016

CODE IDENTITY NUMBER	
-------------------------	--

01295

SIZE

**B**

DRAWING NO.
-------------

AWR1243BOOST

REV

1

Revision\_History

SHEET 17 OF 18

8	7	6	5	4	3	2	1
						REVISIONS	
						SEE SHEET 2	
D							D
C							C
B							B
A							A

FD1

FD2

FD3

FD4

FD5

FD6

PCB LOGO

TEXAS INSTRUMENTS

PCB LOGO

ESD SENSITIVE

PCB LOGO

FCC DISCLAIMER

PCB LOGO

LAUNCHPAD COMPATIBLE

PCB LOGO

ROHS EXEMPT

PCB LABELS : THESE LABELS NEED TO BE PUT ON THE ASSEMBLED PCB

1) TOP SIDE OF THE PCB ->      AWR1243BOOST  
REV A

2) BOTTOM SIDE OF THE PCB ->      AWR1243BOOST  
REV A

ASSEMBLY NOTES:

ASSEMBLIES MUST BE CLEAN AND FREE FROM FLUX AND ALL CONTAMINANTS. USE OF NO CLEAN FLUX IS NOT ACCEPTABLE

ASSEMBLIES MUST COMPLY WITH WORKMANSHIP STANDARDS IPC-A-610 CLASS 2, UNLESS OTHERWISE SPECIFIED

COMPONENTS MARKED "DNI = TRUE" WILL NOT BE ASSEMBLED

TEXAS INSTRUMENTS

SEMICONDUCTOR OPERATIONS

09/5/2016

SIZE

B

DRAWING NO.

AWR1243BOOST

REV

A

Hardware

SHEET 18 OF 18

CODE IDENTITY NUMBER

01295